

Appl. No. 10/510,591 Docket No. NL02 0327US
Amdt. dated December 12, 2005
Response to Notice of Non-Compliant Amendment of 30-NOV-2005

Amendments to the Specification

In the Specification, Abstract, please make the following changes.

On page 12, delete the second paragraph, which reads, "Fig. 1."

Also, please remove reference numerals from the Abstract and make changes as shown.

ABSTRACT:

In an example embodiment, the semiconductor device ~~The semiconductor device (10)~~ comprises a carrier (30) and a semiconductor element (20), such as an integrated circuit. The carrier (30) is provided with apertures (15), thereby defining connecting conductors (31-33) having side faces (3). Notches (16) are present in the side faces (3). The semiconductor element (20) is enclosed in an encapsulation (40) that extends into the notches (16) in the carrier (30). As a result, the encapsulation (40) is mechanically anchored in the carrier (30). The semiconductor device (10) can be made in a process wherein, after the encapsulating step, no lithographic steps are necessary.

~~Fig. 1~~